STL220N6F7

N-channel 60 V, 1.2 mΩ typ., 120 A STripFET™ F7 Power MOSFET in a PowerFLAT™ 5x6 package

Datasheet - production data

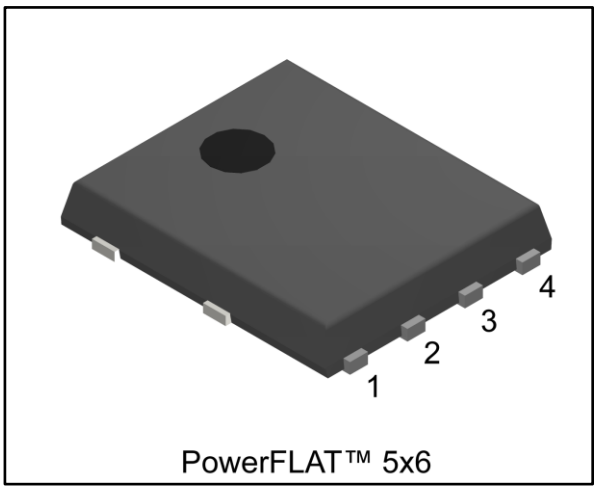
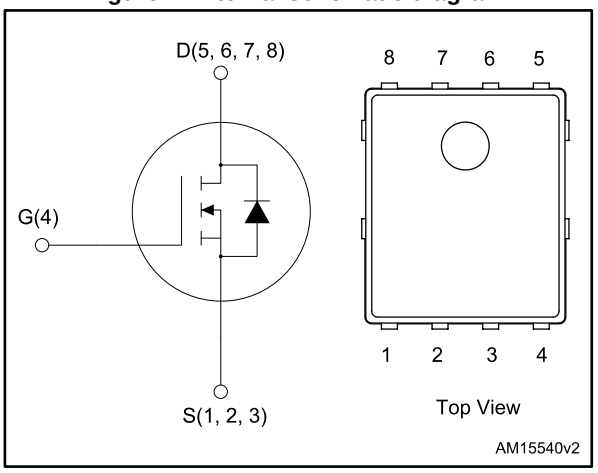


Figure 1: Internal schematic diagram



Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STL220N6F7	60 V	1.4 mΩ	120 A

- Among the lowest $R_{DS(on)}$ on the market
- Excellent FoM (figure of merit)
- Low C_{rss}/C_{iss} ratio for EMI immunity
- High avalanche ruggedness

Applications

- Switching applications

Description

This N-channel Power MOSFET utilizes STripFET™ F7 technology with an enhanced trench gate structure that results in very low on-state resistance, while also reducing internal capacitance and gate charge for faster and more efficient switching.

Table 1: Device summary

Order code	Marking	Package	Packaging
STL220N6F7	220N6F7	PowerFLAT™ 5x6	Tape and reel

Contents

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	60	V
V_{GS}	Gate-source voltage	±20	V
I_D (1)	Drain current (continuous) at T_C = 25 °C	120	A
I_D (1)	Drain current (continuous) at T_C = 100 °C	120	A
I_{DM} (1)(2)	Drain current (pulsed)	480	A
I_D (3)	Drain current (continuous) at T_{pcb} = 25 °C	40	A
I_D (3)	Drain current (continuous) at T_{pcb} = 100 °C	28.5	A
I_{DM} (2)(3)	Drain current (pulsed)	160	A
E_{AS}	Single pulse avalanche energy (starting T_j =25 °C, I_{AS} = 20 A)	900	mJ
P_{TOT} (1)	Total dissipation at T_C = 25 °C	188	W
P_{TOT} (3)	Total dissipation at T_{pcb} = 25 °C	4.8	W
T_j	Operating junction temperature range	-55 to 175	°C
	Storage temperature range		

Notes:

(1)This value is rated according to $R_{thj\text{-}c}$.

(2)Pulse width limited by safe operating area.

(3)This value is rated according to $R_{thj\text{-}pcb}$.

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj\text{-}pcb}$ (1)	Thermal resistance junction-pcb	31.3	°C/W
$R_{thj\text{-}case}$	Thermal resistance junction-case	0.8	°C/W

Notes:

(1)When mounted on FR-4 board of 1 inch², 2oz Cu, t < 10 s.

2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Table 4: On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 1 mA, V_{GS} = 0 V	60			V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V V_{DS} = 60 V			1	µA
I_{GSS}	Gate-body leakage current	V_{GS} = 20 V, V_{DS} = 0 V			100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	2		4	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 20 A		1.2	1.4	mΩ

Table 5: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 25 V, f = 1 MHz, V_{GS} = 0 V	-	6500	-	pF
C_{oss}	Output capacitance		-	3200	-	pF
C_{rss}	Reverse transfer capacitance		-	230	-	pF
Q_g	Total gate charge	V_{DD} = 30 V, I_D = 40 A, V_{GS} = 0 to 10 V (see *Figure 14: "Test circuit for gate charge behavior"*)	-	98	-	nC
Q_{gs}	Gate-source charge		-	38	-	nC
Q_{gd}	Gate-drain charge		-	28	-	nC

Table 6: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 30 V, I_D = 20 A, R_G = 4.7 Ω, V_{GS} = 10 V (see *Figure 13: "Test circuit for resistive load switching times"* and *Figure 18: "Switching time waveform"*)	-	41	-	ns
t_r	Rise time		-	45	-	ns
$t_{d(off)}$	Turn-off delay time		-	68	-	ns
t_f	Fall time		-	35	-	ns

Table 7: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{SD} (1)	Forward on voltage	I_{SD} = 40 A, V_{GS} = 0 V	-		1.2	V
t_{rr}	Reverse recovery time	I_D = 40 A, di/dt = 100 A/µs V_{DD} = 48 V (see *Figure 15: "Test circuit for inductive load switching and diode recovery times"*)	-	69		ns
Q_{rr}	Reverse recovery charge		-	103		nC
I_{RRM}	Reverse recovery current		-	3		A

Notes:

(1)Pulsed: pulse duration = 300 µs, duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2: Safe operating area

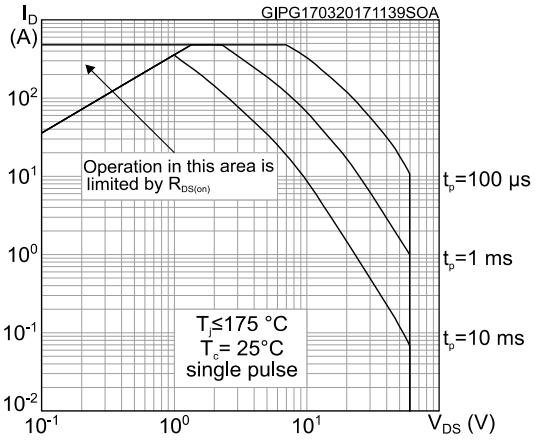


Figure 3: Thermal impedance

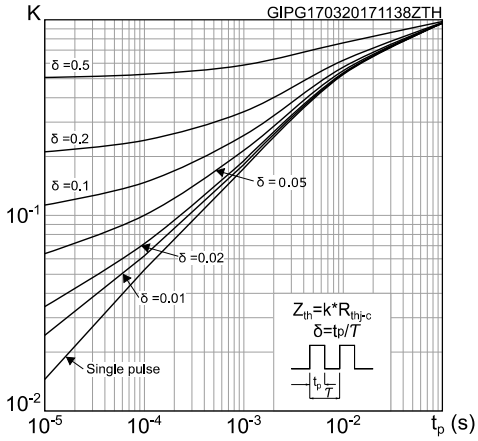


Figure 4: Output characteristics

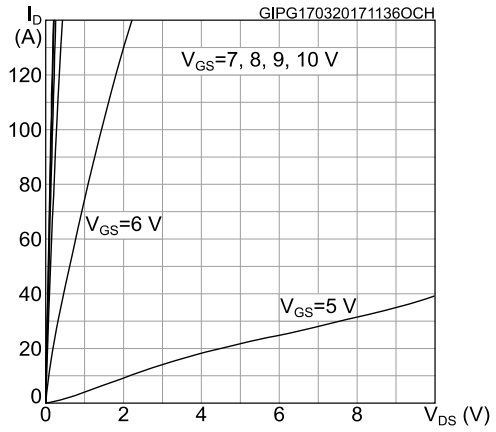


Figure 5: Transfer characteristics

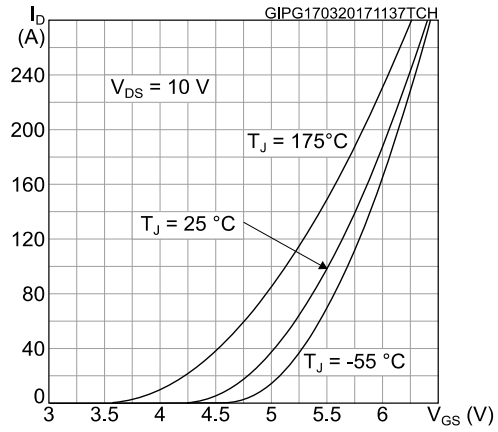


Figure 6: Static drain-source on-resistance

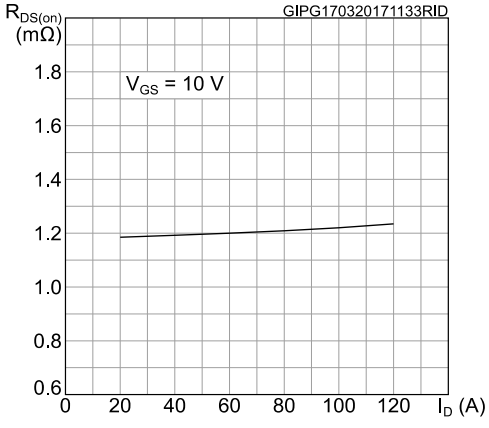


Figure 7: Gate charge vs gate-source voltage

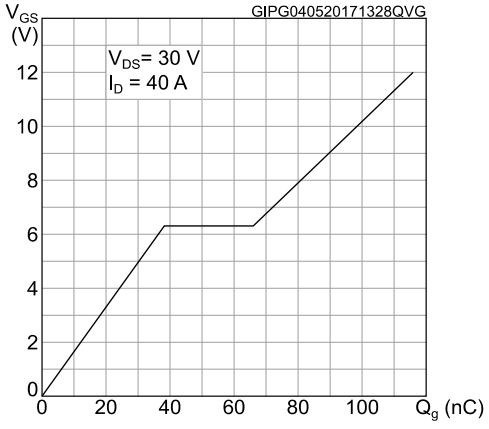


Figure 8: Capacitance variations

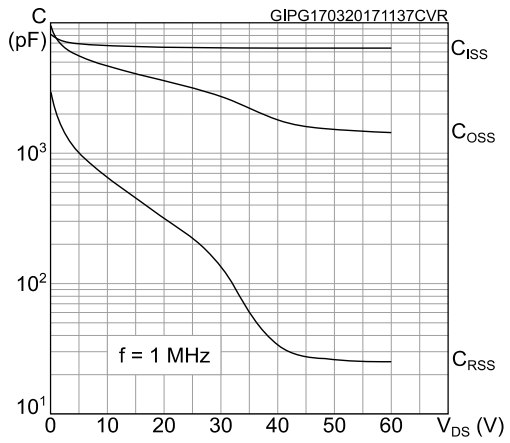


Figure 9: Normalized gate threshold voltage vs temperature

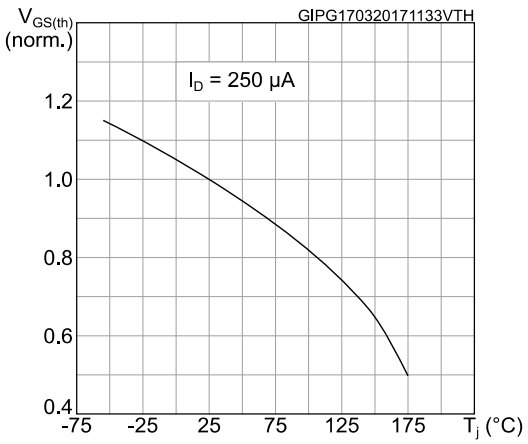


Figure 10: Normalized on-resistance vs temperature

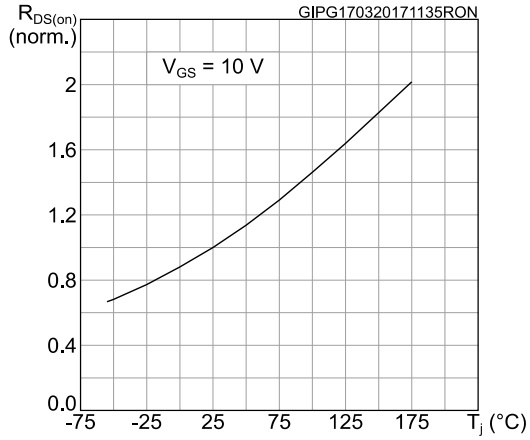


Figure 11: Source-drain diode forward characteristics

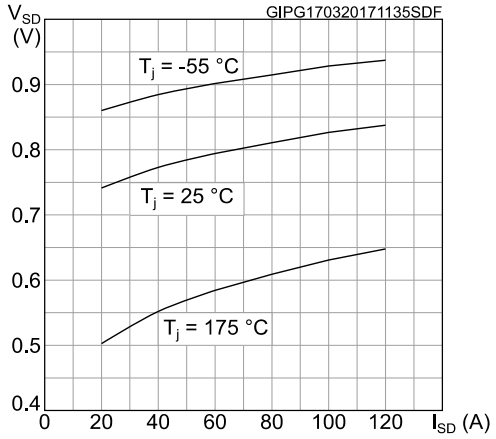
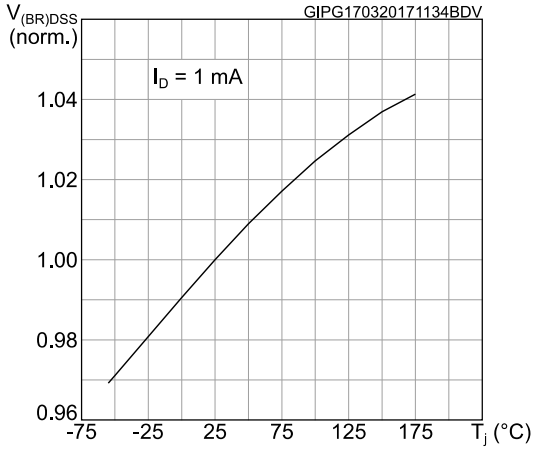


Figure 12: Normalized $V_{(BR)DSS}$ vs temperature



3 Test circuits

Figure 13: Test circuit for resistive load switching times

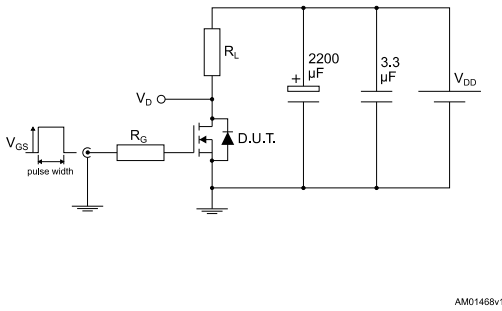


Figure 14: Test circuit for gate charge behavior

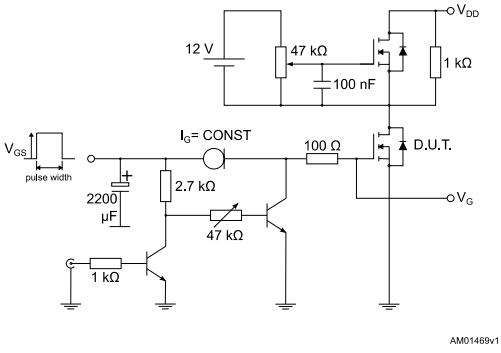


Figure 15: Test circuit for inductive load switching and diode recovery times

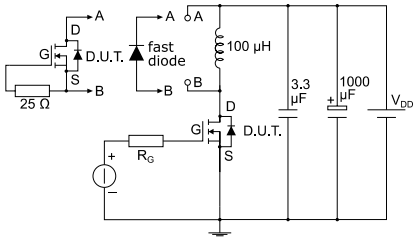


Figure 16: Unclamped inductive load test circuit

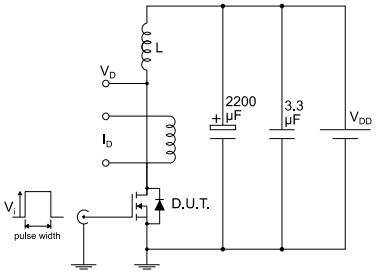


Figure 17: Unclamped inductive waveform

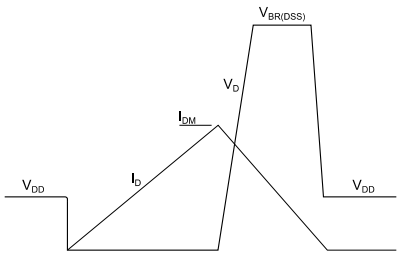
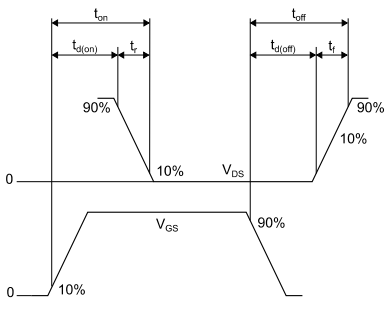


Figure 18: Switching time waveform



4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: ***www.st.com***. ECOPACK® is an ST trademark.

4.1 PowerFLAT 5x6 type C package mechanical data

Figure 19: PowerFLAT™ 5x6 type C package outline

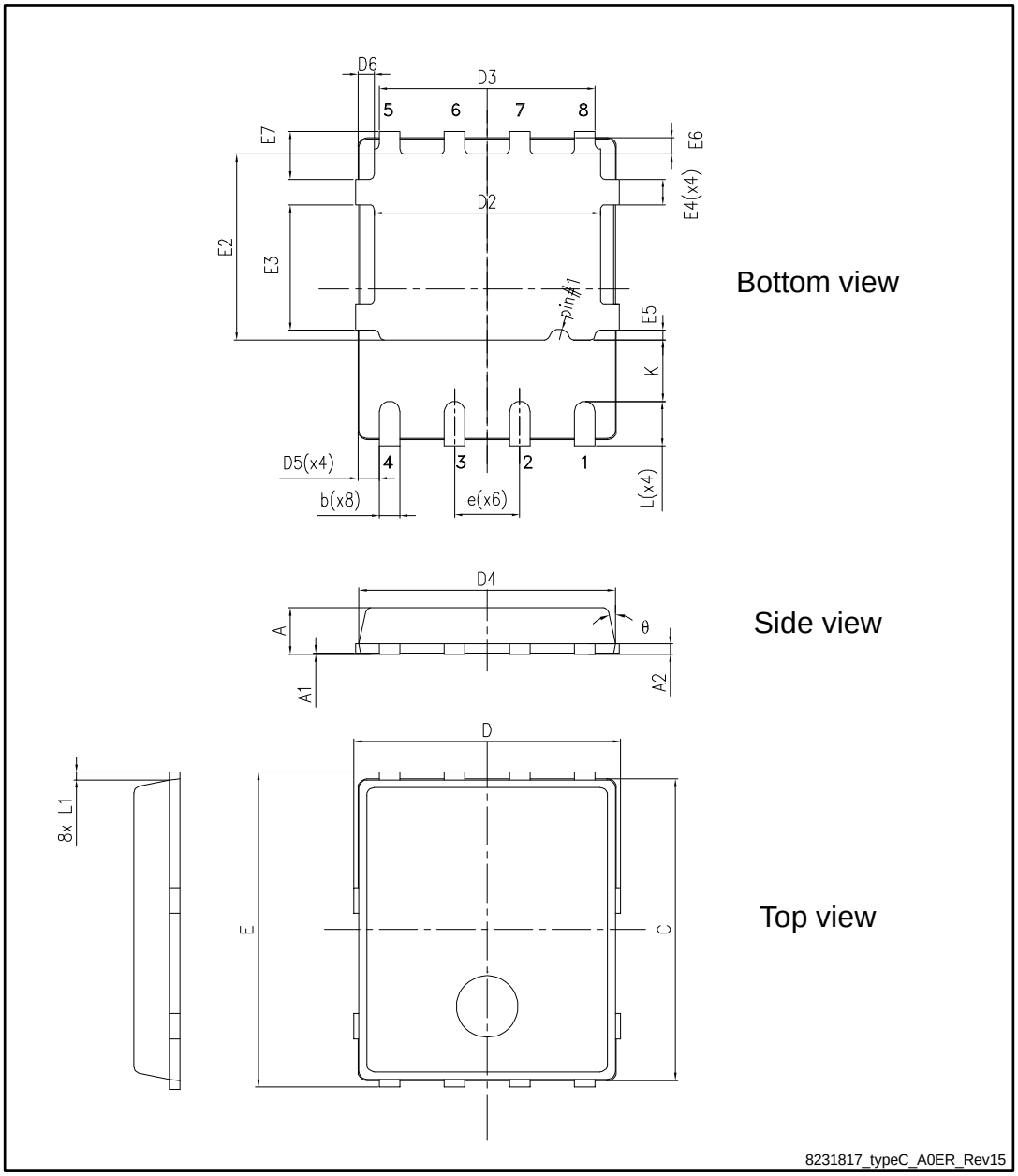
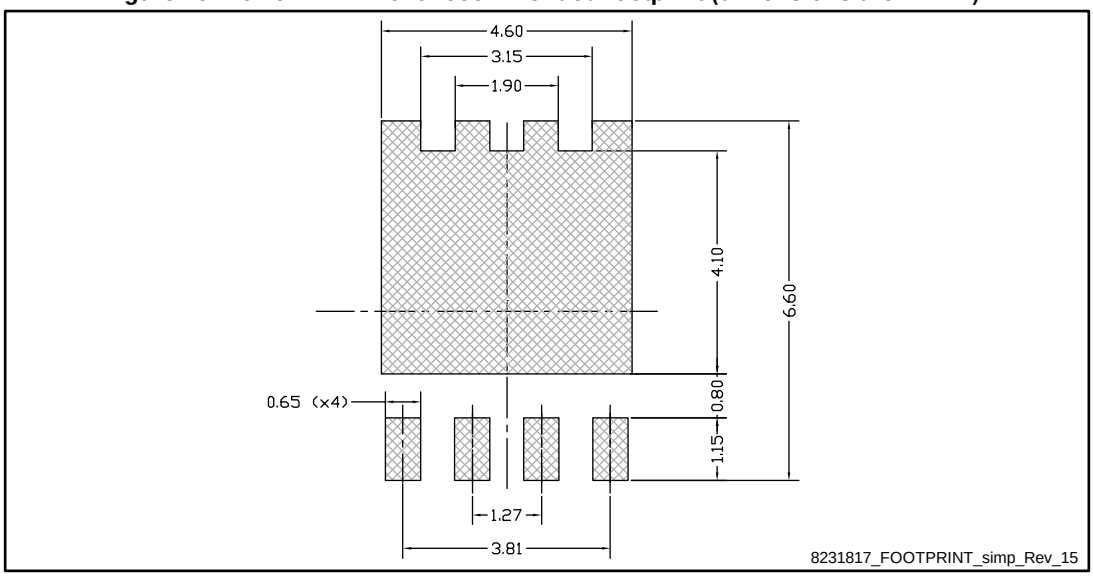


Table 8: PowerFLAT™ 5x6 type C package mechanical data

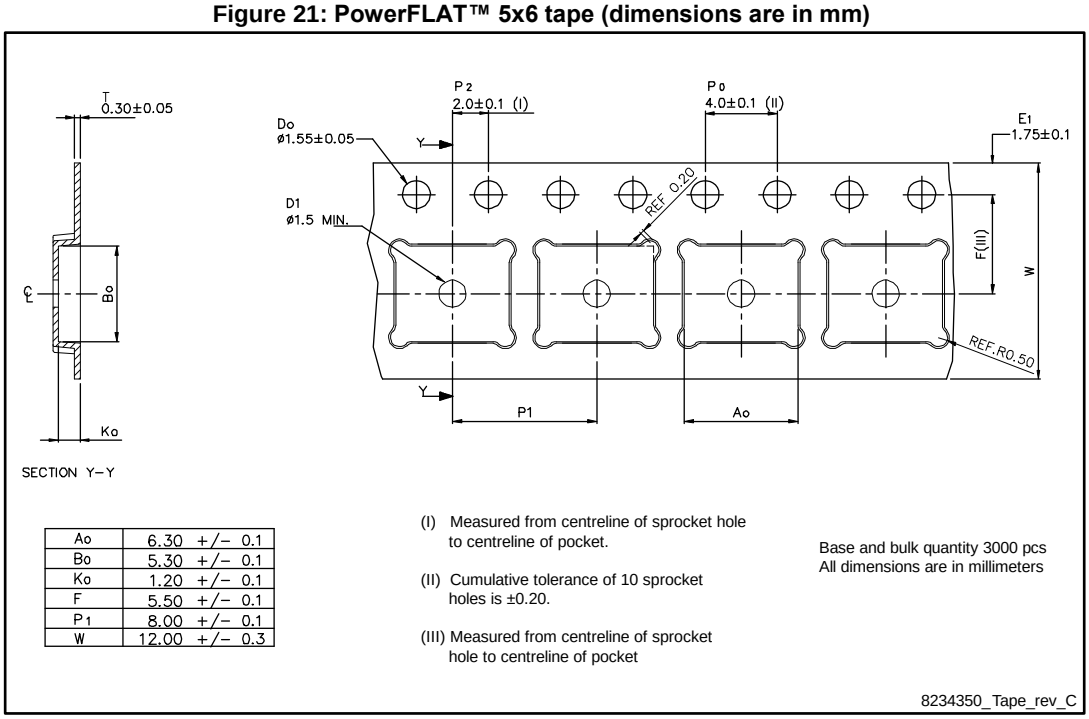
Dim.	mm		
	Min.	Typ.	Max.
A	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
C	5.80	6.00	6.20
D	5.00	5.20	5.40
D2	4.15		4.45
D3	4.05	4.20	4.35
D4	4.80	5.00	5.20
D5	0.25	0.40	0.55
D6	0.15	0.30	0.45
e		1.27	
E	5.95	6.15	6.35
E2	3.50		3.70
E3	2.35		2.55
E4	0.40		0.60
E5	0.08		0.28
E6	0.20	0.325	0.45
E7	0.75	0.90	1.05
K	1.05		1.35
L	0.725		1.025
L1	0.05	0.15	0.25
θ	0°		12°

Figure 20: PowerFLAT™ 5x6 recommended footprint (dimensions are in mm)



4.2 PowerFLAT 5x6 packaging information

Figure 21: PowerFLAT™ 5x6 tape (dimensions are in mm)



Ao	6.30 +/– 0.1
Bo	5.30 +/– 0.1
Ko	1.20 +/– 0.1
F	5.50 +/– 0.1
P1	8.00 +/– 0.1
W	12.00 +/– 0.3

Figure 22: PowerFLAT™ 5x6 package orientation in carrier tape

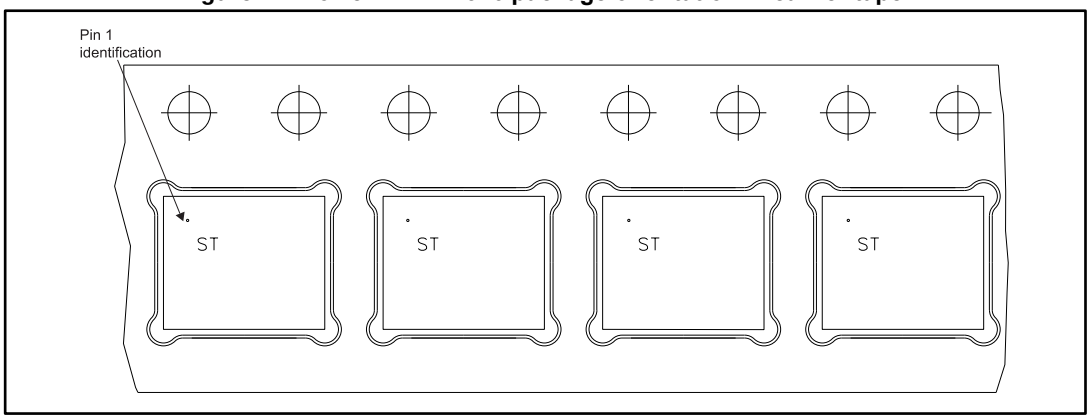
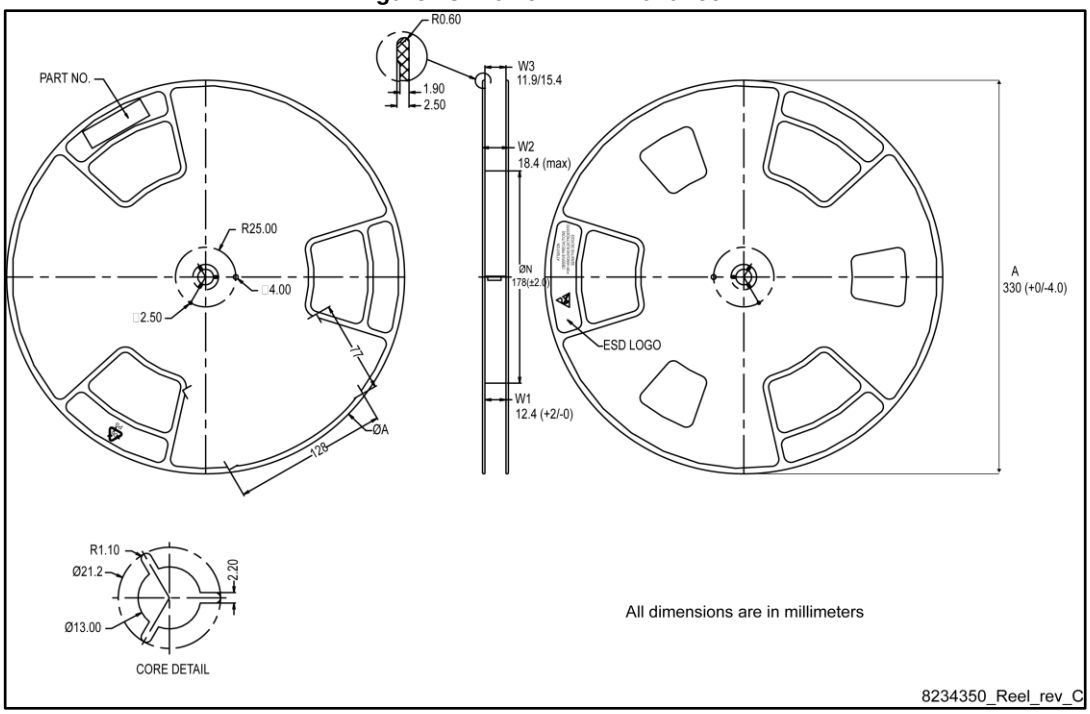


Figure 23: PowerFLAT™ 5x6 reel



5 Revision history

Table 9: Document revision history

Date	Revision	Changes
13-Jun-2014	1	First release.
22-Sep-2014	2	Updated title, features and description in cover page. Updated *Table 2: "Absolute maximum ratings", Table 4: "On /off states", Table 5: "Dynamic", Table 6: "Switching times" and Table 7: "Source-drain diode".* Added *Section 3: "Electrical characteristics (curves)".*
14-Jan-2015	3	Document status promoted from preminary to production data.
02-May-2017	4	Modified title and features table on cover page. Modified *Table 2: "Absolute maximum ratings"*, *Table 4: "On /off states"*, *Table 5: "Dynamic"*, *Table 6: "Switching times"* and *Table 7: "Source-drain diode"*. Modified *Section 2.1: "Electrical characteristics (curves)"*. Minor text changes.

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